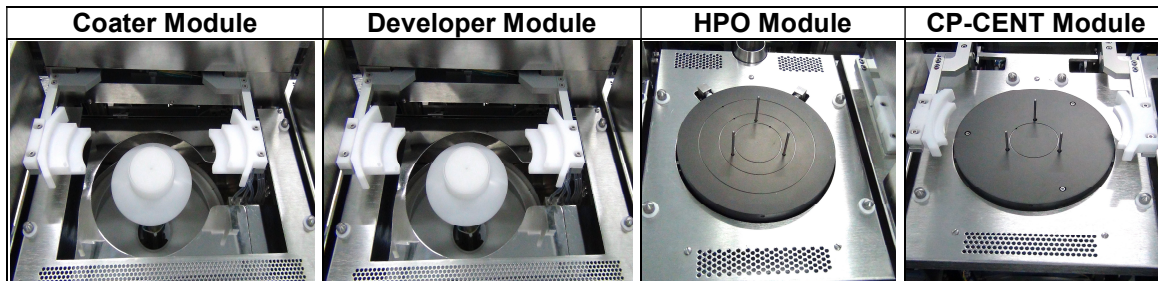


PCT-100RRE TRACK SYSTEM

MASS PRODUCTION WITH DUAL TRACKS (1 COATER, 1 DEVELOPER) TOOL SET

Please contact Sales sales@picotrack.com for more information



Track System Specification	Description																								
System designed	US Standard System																								
System Configuration	<table border="1"> <thead> <tr> <th colspan="6">RANDOM ROBOT ARM # 2</th> </tr> </thead> <tbody> <tr> <td>TRACK #2</td> <td>SEND</td> <td>DEV</td> <td>HPO</td> <td>CP-CENT</td> <td>REC</td> </tr> <tr> <td>TRACK #1</td> <td>SEND</td> <td>COAT</td> <td>HPO</td> <td>CP-CENT</td> <td>REC</td> </tr> <tr> <th colspan="6">RANDOM ROBOT ARM # 1</th> </tr> </tbody> </table>	RANDOM ROBOT ARM # 2						TRACK #2	SEND	DEV	HPO	CP-CENT	REC	TRACK #1	SEND	COAT	HPO	CP-CENT	REC	RANDOM ROBOT ARM # 1					
RANDOM ROBOT ARM # 2																									
TRACK #2	SEND	DEV	HPO	CP-CENT	REC																				
TRACK #1	SEND	COAT	HPO	CP-CENT	REC																				
RANDOM ROBOT ARM # 1																									
(*Configuration available upon request)																									
System dimension	Length: 60" ; Width: 52" ; Height: 70"																								
Wafer size (workable dual size)	Up to 4" (150mm) or 2" & 4" auto conversion																								
Wafer shape	Round/Square/Rectangular/Triangle/Special																								
Wafer material	Silicon/Sapphire/GaAs/ Ceramic...																								
Wafer sensor	Optical sensor mapping																								
System controller	PC & PLC Controller with Windows OS based																								
Chemical canister cabinet	Solvent (EBR, HMDS, Cleaning...), developer liquid																								
Pumps cabinet	Photoresist pumps (IDI, Cybor..), dispenser unit, & photoresist bottles																								
Indexer wafer cassettes capacity	4 Indexers																								
Shuttle Robot Arm	2 Robot arms and dual end effectors																								
System Fan Filter Unit (FFU)	Optional																								
System SECs/GEM	Optional																								
Coater	1 module																								
Catch Cup Set	Fixed position																								
Spindle Unit	Up/down motion																								
Maximum spin speed	6000 rpm																								
Spin motor type	Servo																								
Spin speed accuracy	± 3 rpm																								
Acceleration range	0-50000 rpm/sec																								
Dispense arm accuracy	± 0.1 mm																								
Wafer centering tolerance	± 0.1 mm																								
Dispense arm motion control	Stepper motor and driver																								
Dispense arm & nozzles	3x or more (3/16" or 1/4" OD) (Standard)																								
Dispense method	Static and traverse																								
Pre-dispense function	Yes																								
Top/Bottom EBR	Yes																								
Catch-cup rinse(CCR)	Optional																								
Cleaning tip nozzle	Optional																								
Humidity & Temperature control	Optional																								
Photoresist temperature control	Optional (≤ 1°C; 10-50°C range)																								
Developer	1 module																								
Catch Cup Set	Fixed position																								
Spindle Unit	Up/down motion																								
Maximum spin speed	6000 rpm																								
Spin motor type	Servo																								
Spin speed accuracy	± 3 rpm																								
Acceleration range	0-50000 rpm/sec																								
Spin direction	Clockwise (+) & counter clockwise (-)																								
Dispense arm motion control	Stepper motor drive and rotation																								
Dispense arm accuracy	± 0.1 mm																								

Wafer centering tolerance	± 0.1 mm
Dispense arm nozzles	1 Spray+ 1 Stream or 2 spray+ 2 stream (Standard)
Negative developer nozzles	Cone or fan spray with N2 air assist (Upon request)
Developer dispense type	Stream, Puddle, Fan spray, Cone spray....
Dispense method	Static, traverse and sweep
DI water top and back side rinse	Yes
N2 Air Ring back side	Yes
N2 Blow-off top nozzle	Optional
Developer liquid Temp. controller	Optional (≤ 1°C; 10-50°C range)
Hot Plate Oven (HPO)	2 modules
HPO block type	Aluminum anodized with vacuum slots or standoff proximity
Temperature thermal probe	RTD or TC
HPO Temperature controller	Watlow P.I.D with over heating protection
Temperature range	25-250°C, Δt: 50°C ≤ 200s (>250°C option)
Temperature uniformity	± 1°C (25-150°C), ± 2°C (151-250°C)
Wafer carrier	3 pins controlled by stepper motor
Bake method	Contact/ Proximity bake/ or fixed proximity
Chill Plate & Centering (CP-CENT)	2 modules
Chill Plate block type	Aluminum anodized with vacuum slots or proximity
Chill Plate Temperature control	House cooling water with flowmeter (18°C to 30°C)
Chill method	Contact
Cooling Water Temperature controller	Optional
Wafer carrier	3 pins controlled by air cylinder
Wafer Centering	Integrated